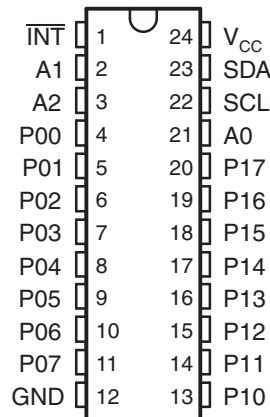
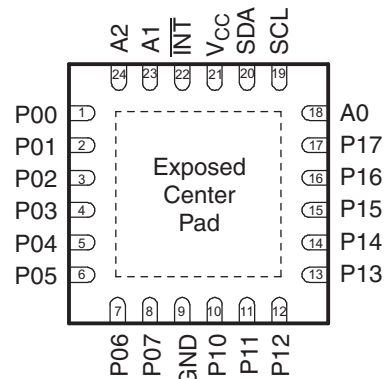


LOW VOLTAGE 16-BIT I²C AND SMBus I/O EXPANDER WITH INTERRUPT OUTPUT AND CONFIGURATION REGISTERS

FEATURES

- Low Standby-Current Consumption of 3 μ A Max
- I²C to Parallel Port Expander
- Open-Drain Active-Low Interrupt Output
- 5-V Tolerant I/O Ports
- Compatible With Most Microcontrollers
- 400-kHz Fast I²C Bus
- Address by Three Hardware Address Pins for Use of up to Eight Devices
- Polarity Inversion Register
- Latched Outputs With High-Current Drive Capability for Directly Driving LEDs
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

**PW PACKAGE
(TOP VIEW)**

**RTW PACKAGE
(TOP VIEW)**


The exposed center pad, if used, must be connected as a secondary ground or left electrically open.

DESCRIPTION/ORDERING INFORMATION

This 16-bit I/O expander for the two-line bidirectional bus (I²C) is designed for 1.65-V to 5.5-V V_{CC} operation. It provides general-purpose remote I/O expansion for most microcontroller families via the I²C interface [serial clock (SCL), serial data (SDA)].

The TCA9555 consists of two 8-bit Configuration (input or output selection), Input Port, Output Port, and Polarity Inversion (active high or active low operation) registers. At power on, the I/Os are configured as inputs. The system master can enable the I/Os as either inputs or outputs by writing to the I/O configuration bits. The data for each input or output is kept in the corresponding Input or Output register. The polarity of the Input Port register can be inverted with the Polarity Inversion register. All registers can be read by the system master.

The system master can reset the TCA9555 in the event of a timeout or other improper operation by utilizing the power-on reset feature, which puts the registers in their default state and initializes the I²C/SMBus state machine.

The TCA9555 open-drain interrupt ($\overline{\text{INT}}$) output is activated when any input state differs from its corresponding Input Port register state and is used to indicate to the system master that an input state has changed.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

$\overline{\text{INT}}$ can be connected to the interrupt input of a microcontroller. By sending an interrupt signal on this line, the remote I/O can inform the microcontroller if there is incoming data on its ports without having to communicate via the I²C bus. Thus, the TCA9555 can remain a simple slave device.

The device outputs (latched) have high-current drive capability for directly driving LEDs.

Although pin-to-pin and I²C-address is compatible with the PCF8575, software changes are required due to the enhancements.

The TCA9555 is identical to the TCA9535, except for the inclusion of the internal I/O pullup resistor, which pulls the I/O to a default high when configured as an input and undriven.

Three hardware pins (A0, A1, and A2) are used to program and vary the fixed I²C address and allow up to eight devices to share the same I²C bus or SMBus. The fixed I²C address of the TCA9555 is the same as the PCF8575, PCF8575C, and PCF8574, allowing up to eight of these devices in any combination to share the same I²C bus or SMBus.

ORDERING INFORMATION⁽¹⁾

| T _A | PACKAGE ⁽²⁾ | | ORDERABLE PART NUMBER | TOP-SIDE MARKING |
|----------------|------------------------|--------------|-----------------------|------------------|
| –40°C to 85°C | TSSOP – PW | Reel of 2000 | TCA9555PWR | PW555 |
| | QFN – RTW | Reel of 3000 | TCA9555RTWR | PW555 |

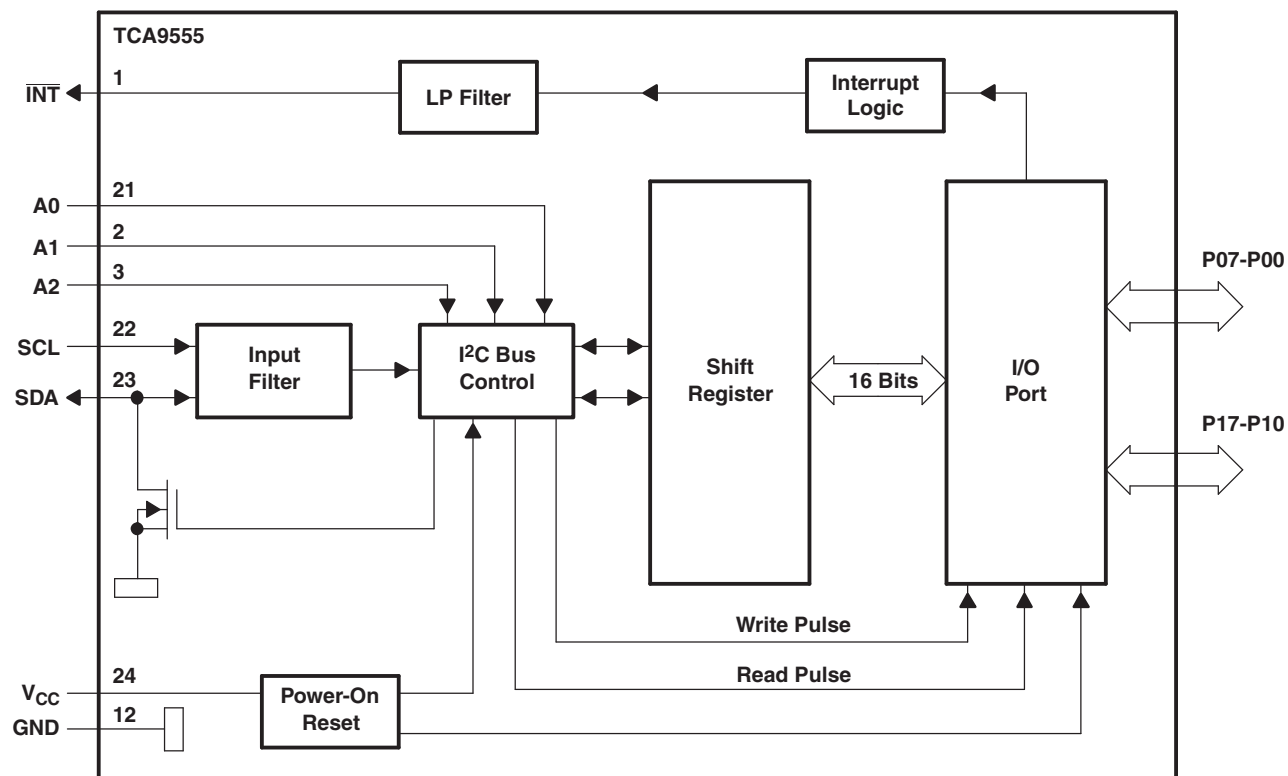
(1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.

(2) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.

TERMINAL FUNCTIONS

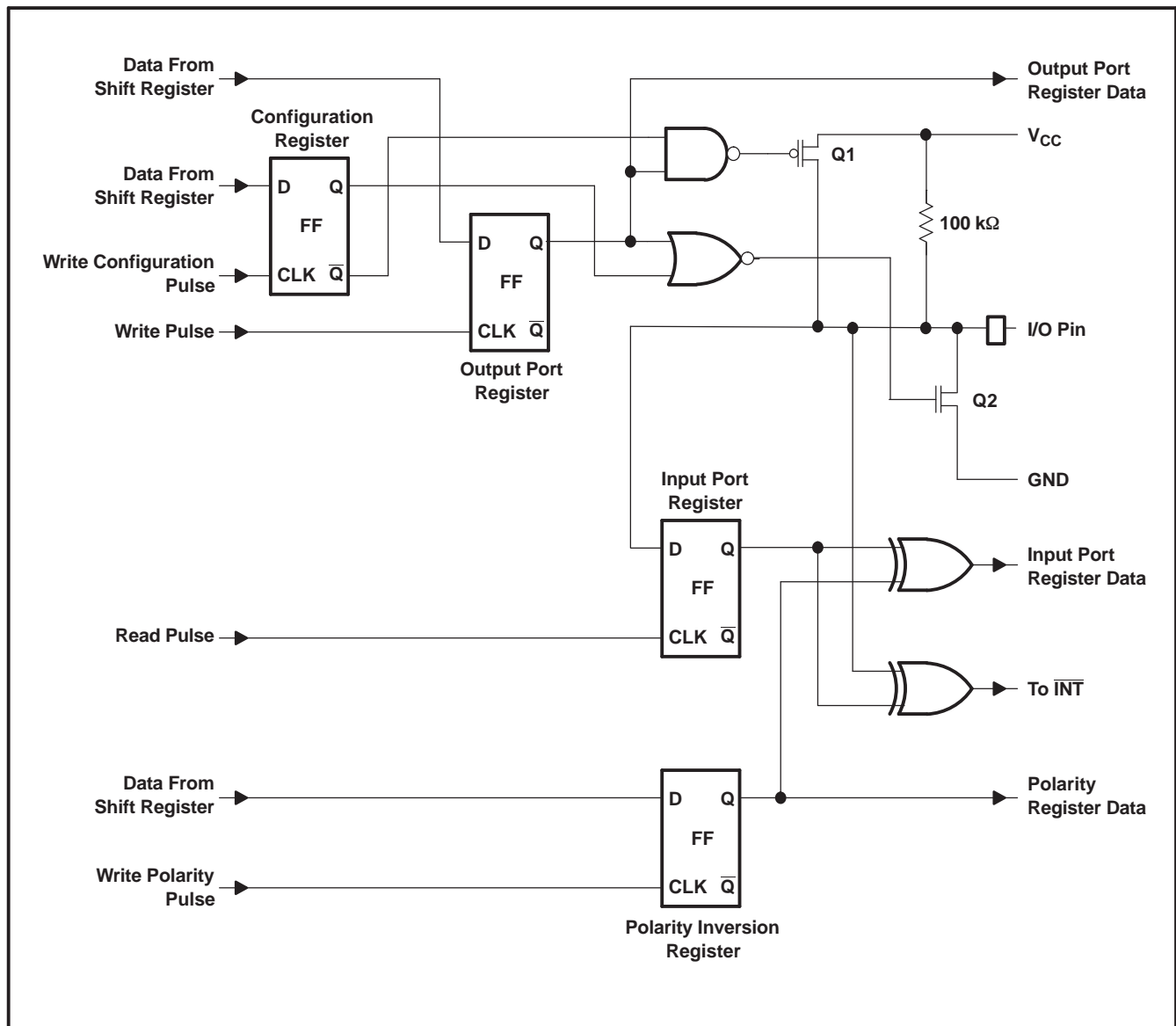
| NO. | | NAME | DESCRIPTION |
|------------|-----------|-------------------------|--|
| TSSOP (PW) | QFN (RTW) | | |
| 1 | 22 | $\overline{\text{INT}}$ | Interrupt output. Connect to V_{CC} through a pullup resistor. |
| 2 | 23 | A1 | Address input 1. Connect directly to V_{CC} or ground. |
| 3 | 24 | A2 | Address input 2. Connect directly to V_{CC} or ground. |
| 4 | 1 | P00 | P-port input/output. Push-pull design structure. At power on, P00 is configured as an input. |
| 5 | 2 | P01 | P-port input/output. Push-pull design structure. At power on, P01 is configured as an input. |
| 6 | 3 | P02 | P-port input/output. Push-pull design structure. At power on, P02 is configured as an input. |
| 7 | 4 | P03 | P-port input/output. Push-pull design structure. At power on, P03 is configured as an input. |
| 8 | 5 | P04 | P-port input/output. Push-pull design structure. At power on, P04 is configured as an input. |
| 9 | 6 | P05 | P-port input/output. Push-pull design structure. At power on, P05 is configured as an input. |
| 10 | 7 | P06 | P-port input/output. Push-pull design structure. At power on, P06 is configured as an input. |
| 11 | 8 | P07 | P-port input/output. Push-pull design structure. At power on, P07 is configured as an input. |
| 12 | 9 | GND | Ground |
| 13 | 10 | P10 | P-port input/output. Push-pull design structure. At power on, P10 is configured as an input. |
| 14 | 11 | P11 | P-port input/output. Push-pull design structure. At power on, P11 is configured as an input. |
| 15 | 12 | P12 | P-port input/output. Push-pull design structure. At power on, P12 is configured as an input. |
| 16 | 13 | P13 | P-port input/output. Push-pull design structure. At power on, P13 is configured as an input. |
| 17 | 14 | P14 | P-port input/output. Push-pull design structure. At power on, P14 is configured as an input. |
| 18 | 15 | P15 | P-port input/output. Push-pull design structure. At power on, P15 is configured as an input. |
| 19 | 16 | P16 | P-port input/output. Push-pull design structure. At power on, P16 is configured as an input. |
| 20 | 17 | P17 | P-port input/output. Push-pull design structure. At power on, P17 is configured as an input. |
| 21 | 18 | A0 | Address input 0. Connect directly to V_{CC} or ground. |
| 22 | 19 | SCL | Serial clock bus. Connect to V_{CC} through a pullup resistor. |
| 23 | 20 | SDA | Serial data bus. Connect to V_{CC} through a pullup resistor. |
| 24 | 21 | V_{CC} | Supply voltage |

LOGIC DIAGRAM (POSITIVE LOGIC)



- A. Pin numbers shown are for the PW package.
- B. All I/Os are set to inputs at reset.

SIMPLIFIED SCHEMATIC OF P-PORT I/Os



I/O Port

When an I/O is configured as an input, FETs Q1 and Q2 are off, creating a high-impedance input. The input voltage may be raised above V_{CC} to a maximum of 5.5 V.

If the I/O is configured as an output, Q1 or Q2 is enabled, depending on the state of the Output Port register. In this case, there are low-impedance paths between the I/O pin and either V_{CC} or GND. The external voltage applied to this I/O pin should not exceed the recommended levels for proper operation.

I²C Interface

The bidirectional I²C bus consists of the serial clock (SCL) and serial data (SDA) lines. Both lines must be connected to a positive supply via a pullup resistor when connected to the output stages of a device. Data transfer may be initiated only when the bus is not busy.

I²C communication with this device is initiated by a master sending a Start condition, a high-to-low transition on the SDA input/output while the SCL input is high (see Figure 1). After the Start condition, the device address byte is sent, MSB first, including the data direction bit (R/W). This device does not respond to the general call address.

After receiving the valid address byte, this device responds with an ACK, a low on the SDA input/output during the high of the ACK-related clock pulse. The address inputs (A0–A2) of the slave device must not be changed between the Start and Stop conditions.

On the I²C bus, only one data bit is transferred during each clock pulse. The data on the SDA line must remain stable during the high pulse of the clock period, as changes in the data line at this time are interpreted as control commands (Start or Stop) (see Figure 2).

A Stop condition, a low-to-high transition on the SDA input/output while the SCL input is high, is sent by the master (see Figure 1).

Any number of data bytes can be transferred from the transmitter to the receiver between the Start and the Stop conditions. Each byte of eight bits is followed by one ACK bit. The transmitter must release the SDA line before the receiver can send an ACK bit. The device that acknowledges must pull down the SDA line during the ACK clock pulse so that the SDA line is stable low during the high pulse of the ACK-related clock period (see Figure 3). When a slave receiver is addressed, it must generate an ACK after each byte is received. Similarly, the master must generate an ACK after each byte that it receives from the slave transmitter. Setup and hold times must be met to ensure proper operation.

A master receiver signals an end of data to the slave transmitter by not generating an acknowledge (NACK) after the last byte has been clocked out of the slave. This is done by the master receiver by holding the SDA line high. In this event, the transmitter must release the data line to enable the master to generate a Stop condition.

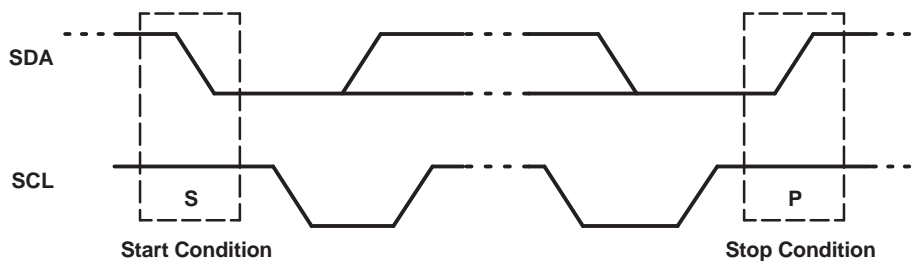


Figure 1. Definition of Start and Stop Conditions

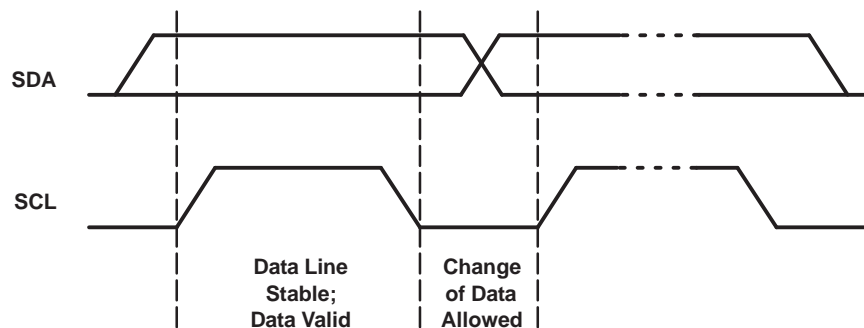


Figure 2. Bit Transfer

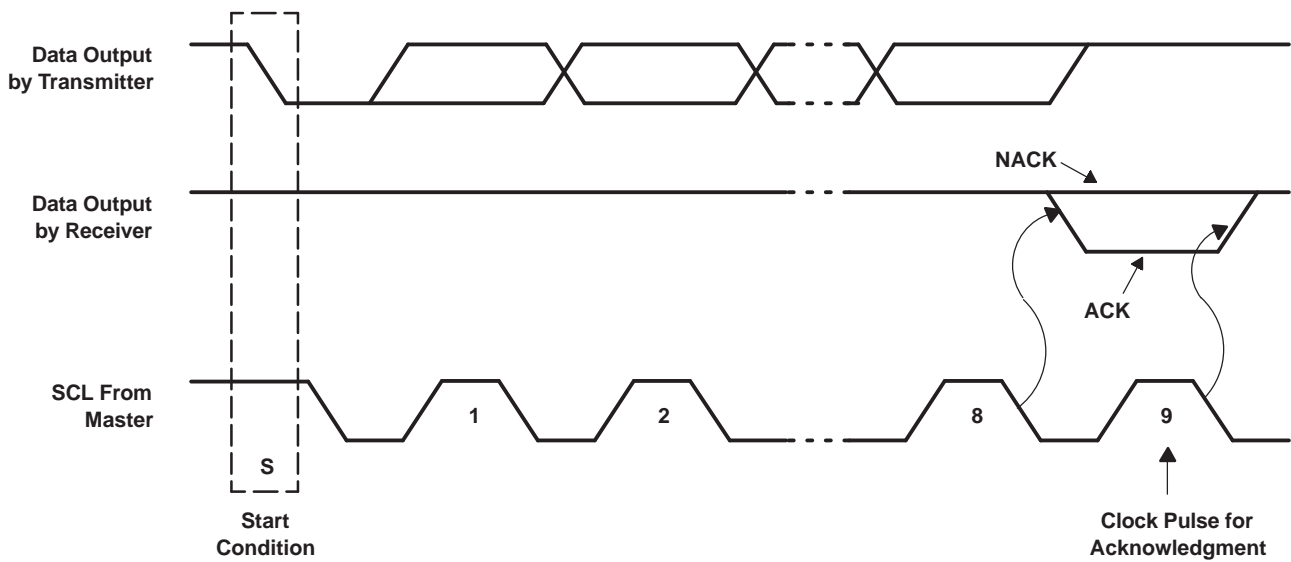


Figure 3. Acknowledgment on I²C Bus

Interface Definition

| BYTE | BIT | | | | | | | |
|--------------------------------|---------|-----|-----|-----|-----|-----|-----|---------|
| | 7 (MSB) | 6 | 5 | 4 | 3 | 2 | 1 | 0 (LSB) |
| I ² C slave address | L | H | L | L | A2 | A1 | A0 | R/W |
| P0x I/O data bus | P07 | P06 | P05 | P04 | P03 | P02 | P01 | P00 |
| P1x I/O data bus | P17 | P16 | P15 | P14 | P13 | P12 | P11 | P10 |

Device Address

Figure 4 shows the address byte of the TCA9555.

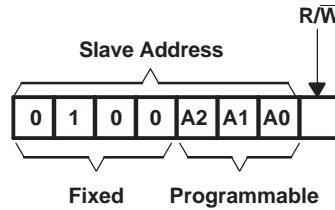


Figure 4. TCA9555 Address

Address Reference

| INPUTS | | | I ² C BUS SLAVE ADDRESS |
|--------|----|----|------------------------------------|
| A2 | A1 | A0 | |
| L | L | L | 32 (decimal), 20 (hexadecimal) |
| L | L | H | 33 (decimal), 21 (hexadecimal) |
| L | H | L | 34 (decimal), 22 (hexadecimal) |
| L | H | H | 35 (decimal), 23 (hexadecimal) |
| H | L | L | 36 (decimal), 24 (hexadecimal) |
| H | L | H | 37 (decimal), 25 (hexadecimal) |
| H | H | L | 38 (decimal), 26 (hexadecimal) |
| H | H | H | 39 (decimal), 27 (hexadecimal) |

The last bit of the slave address defines the operation (read or write) to be performed. A high (1) selects a read operation, while a low (0) selects a write operation.

Control Register and Command Byte

Following the successful acknowledgment of the address byte, the bus master sends a command byte that is stored in the control register in the TCA9555. Three bits of this data byte state the operation (read or write) and the internal register (input, output, polarity inversion, or configuration) that will be affected. This register can be written or read through the I²C bus. The command byte is sent only during a write transmission.

Once a command byte has been sent, the register that was addressed continues to be accessed by reads until a new command byte has been sent.

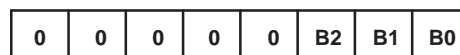


Figure 5. Control Register Bits

Command Byte

| CONTROL REGISTER BITS | | | COMMAND BYTE (HEX) | REGISTER | PROTOCOL | POWER-UP DEFAULT |
|-----------------------|----|----|--------------------|---------------------------|-----------------|------------------|
| B2 | B1 | B0 | | | | |
| 0 | 0 | 0 | 0x00 | Input Port 0 | Read byte | xxxx xxxx |
| 0 | 0 | 1 | 0x01 | Input Port 1 | Read byte | xxxx xxxx |
| 0 | 1 | 0 | 0x02 | Output Port 0 | Read/write byte | 1111 1111 |
| 0 | 1 | 1 | 0x03 | Output Port 1 | Read/write byte | 1111 1111 |
| 1 | 0 | 0 | 0x04 | Polarity Inversion Port 0 | Read/write byte | 0000 0000 |
| 1 | 0 | 1 | 0x05 | Polarity Inversion Port 1 | Read/write byte | 0000 0000 |
| 1 | 1 | 0 | 0x06 | Configuration Port 0 | Read/write byte | 1111 1111 |
| 1 | 1 | 1 | 0x07 | Configuration Port 1 | Read/write byte | 1111 1111 |

Register Descriptions

The Input Port registers (registers 0 and 1) reflect the incoming logic levels of the pins, regardless of whether the pin is defined as an input or an output by the Configuration register. It only acts on read operation. Writes to these registers have no effect. The default value, X, is determined by the externally applied logic level.

Before a read operation, a write transmission is sent with the command byte to indicate to the I²C device that the Input Port register will be accessed next.

Registers 0 and 1 (Input Port Registers)

| | | | | | | | | |
|----------------|-------------|-------------|-------------|-------------|-------------|-------------|-------------|-------------|
| Bit | I0.7 | I0.6 | I0.5 | I0.4 | I0.3 | I0.2 | I0.1 | I0.0 |
| Default | X | X | X | X | X | X | X | X |
| Bit | I1.7 | I1.6 | I1.5 | I1.4 | I1.3 | I1.2 | I1.1 | I1.0 |
| Default | X | X | X | X | X | X | X | X |

The Output Port registers (registers 2 and 3) show the outgoing logic levels of the pins defined as outputs by the Configuration register. Bit values in this register have no effect on pins defined as inputs. In turn, reads from this register reflect the value that is in the flip-flop controlling the output selection, not the actual pin value.

Registers 2 and 3 (Output Port Registers)

| | | | | | | | | |
|----------------|-------------|-------------|-------------|-------------|-------------|-------------|-------------|-------------|
| Bit | O0.7 | O0.6 | O0.5 | O0.4 | O0.3 | O0.2 | O0.1 | O0.0 |
| Default | 1 | 1 | 1 | 1 | 1 | 1 | 1 | 1 |
| Bit | O1.7 | O1.6 | O1.5 | O1.4 | O1.3 | O1.2 | O1.1 | O1.0 |
| Default | 1 | 1 | 1 | 1 | 1 | 1 | 1 | 1 |

The Polarity Inversion registers (registers 4 and 5) allow polarity inversion of pins defined as inputs by the Configuration register. If a bit in this register is set (written with 1), the corresponding port pin's polarity is inverted. If a bit in this register is cleared (written with a 0), the corresponding port pin's original polarity is retained.

Registers 4 and 5 (Polarity Inversion Registers)

| | | | | | | | | |
|----------------|-------------|-------------|-------------|-------------|-------------|-------------|-------------|-------------|
| Bit | N0.7 | N0.6 | N0.5 | N0.4 | N0.3 | N0.2 | N0.1 | N0.0 |
| Default | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 |
| Bit | N1.7 | N1.6 | N1.5 | N1.4 | N1.3 | N1.2 | N1.1 | N1.0 |
| Default | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 |

The Configuration registers (registers 6 and 7) configure the directions of the I/O pins. If a bit in this register is set to 1, the corresponding port pin is enabled as an input with a high-impedance output driver. If a bit in this register is cleared to 0, the corresponding port pin is enabled as an output.

Registers 6 and 7 (Configuration Registers)

| | | | | | | | | |
|----------------|-------------|-------------|-------------|-------------|-------------|-------------|-------------|-------------|
| Bit | C0.7 | C0.6 | C0.5 | C0.4 | C0.3 | C0.2 | C0.1 | C0.0 |
| Default | 1 | 1 | 1 | 1 | 1 | 1 | 1 | 1 |
| Bit | C1.7 | C1.6 | C1.5 | C1.4 | C1.3 | C1.2 | C1.1 | C1.0 |
| Default | 1 | 1 | 1 | 1 | 1 | 1 | 1 | 1 |

Power-On Reset

When power (from 0 V) is applied to V_{CC}, an internal power-on reset holds the TCA9555 in a reset condition until V_{CC} has reached V_{POR}. At that point, the reset condition is released and the TCA9555 registers and I²C/SMBus state machine initialize to their default states. After that, V_{CC} must be lowered to below 0.2 V and then back up to the operating voltage for a power-reset cycle.

Interrupt ($\overline{\text{INT}}$) Output

An interrupt is generated by any rising or falling edge of the port inputs in the input mode. After time, t_{iv} , the signal $\overline{\text{INT}}$ is valid. Resetting the interrupt circuit is achieved when data on the port is changed to the original setting, data is read from the port that generated the interrupt or in a Stop event. Resetting occurs in the read mode at the acknowledge (ACK) bit or not acknowledge (NACK) bit after the falling edge of the SCL signal. Interrupts that occur during the ACK or NACK clock pulse can be lost (or be very short) due to the resetting of the interrupt during this pulse. Each change of the I/Os after resetting is detected and is transmitted as $\overline{\text{INT}}$.

Reading from or writing to another device does not affect the interrupt circuit, and a pin configured as an output cannot cause an interrupt. Changing an I/O from an output to an input may cause a false interrupt to occur if the state of the pin does not match the contents of the Input Port register. Because each 8-bit port is read independently, the interrupt caused by port 0 is not cleared by a read of port 1, or vice versa.

$\overline{\text{INT}}$ has an open-drain structure and requires a pullup resistor to V_{CC} .

Bus Transactions

Data is exchanged between the master and the TCA9555 through write and read commands.

Writes

Data is transmitted to the TCA9555 by sending the device address and setting the least-significant bit to a logic 0 (see Figure 4 for device address). The command byte is sent after the address and determines which register receives the data that follows the command byte.

The eight registers within the TCA9555 are configured to operate as four register pairs. The four pairs are input ports, output ports, polarity inversion ports, and configuration ports. After sending data to one register, the next data byte is sent to the other register in the pair (see Figure 6 and Figure 7). For example, if the first byte is sent to output port (register 3), the next byte is stored in Output Port 0 (register 2).

There is no limitation on the number of data bytes sent in one write transmission. In this way, each 8-bit register may be updated independently of the other registers.

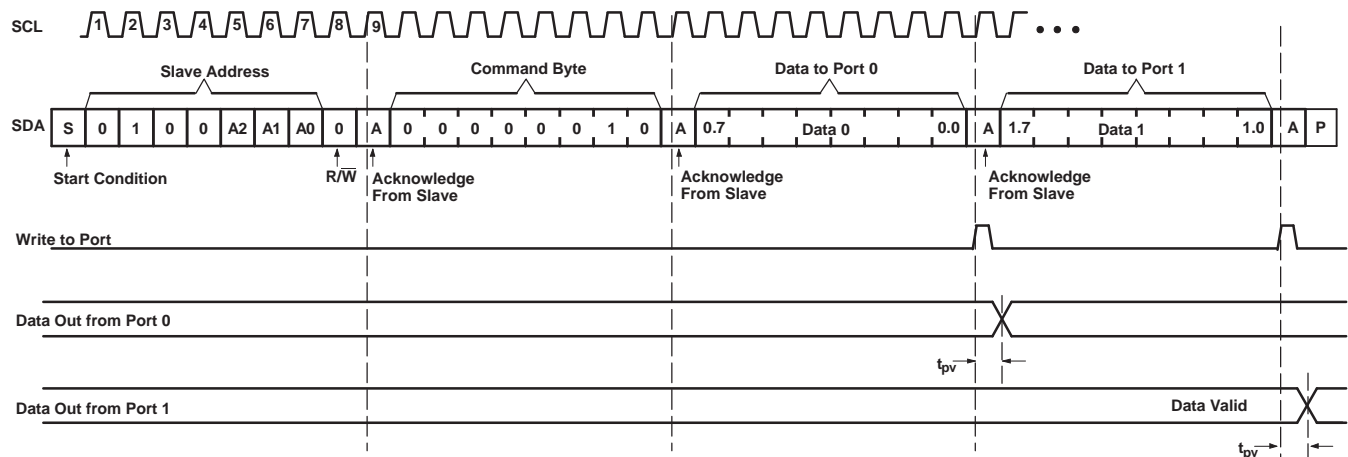


Figure 6. Write to Output Port Registers

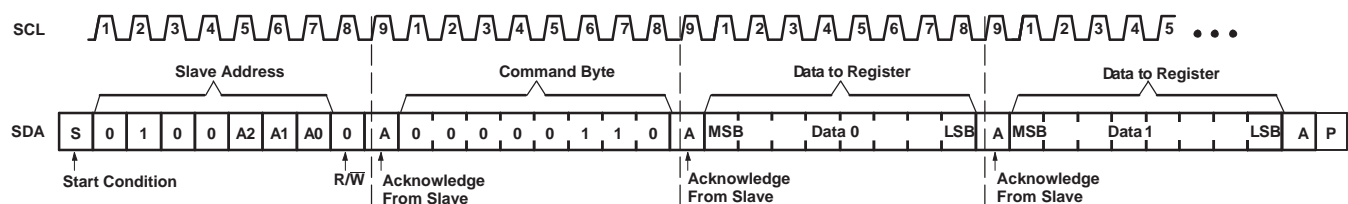


Figure 7. Write to Configuration Registers

Reads

The bus master first must send the TCA9555 address with the least-significant bit set to a logic 0 (see Figure 4 for device address). The command byte is sent after the address and determines which register is accessed. After a restart, the device address is sent again, but this time, the least-significant bit is set to a logic 1. Data from the register defined by the command byte then is sent by the TCA9555 (see Figure 8 through Figure 10).

After a restart, the value of the register defined by the command byte matches the register being accessed when the restart occurred. For example, if the command byte references Input Port 1 before the restart, and the restart occurs when Input Port 0 is being read, the stored command byte changes to reference Input Port 0. The original command byte is forgotten. If a subsequent restart occurs, Input Port 0 is read first. Data is clocked into the register on the rising edge of the ACK clock pulse. After the first byte is read, additional bytes may be read, but the data now reflect the information in the other register in the pair. For example, if Input Port 1 is read, the next byte read is Input Port 0.

Data is clocked into the register on the rising edge of the ACK clock pulse. There is no limitation on the number of data bytes received in one read transmission, but when the final byte is received, the bus master must not acknowledge the data.

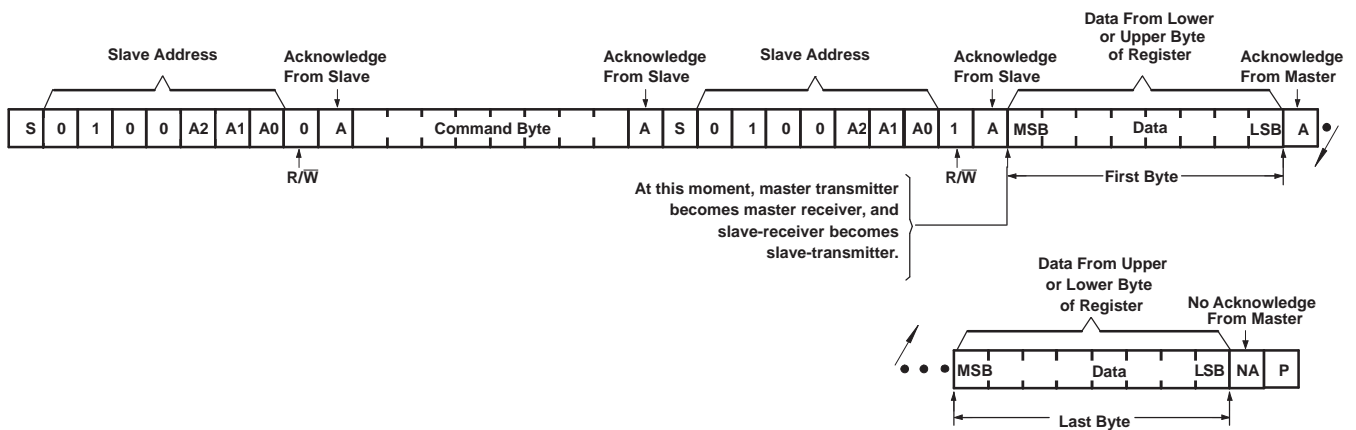
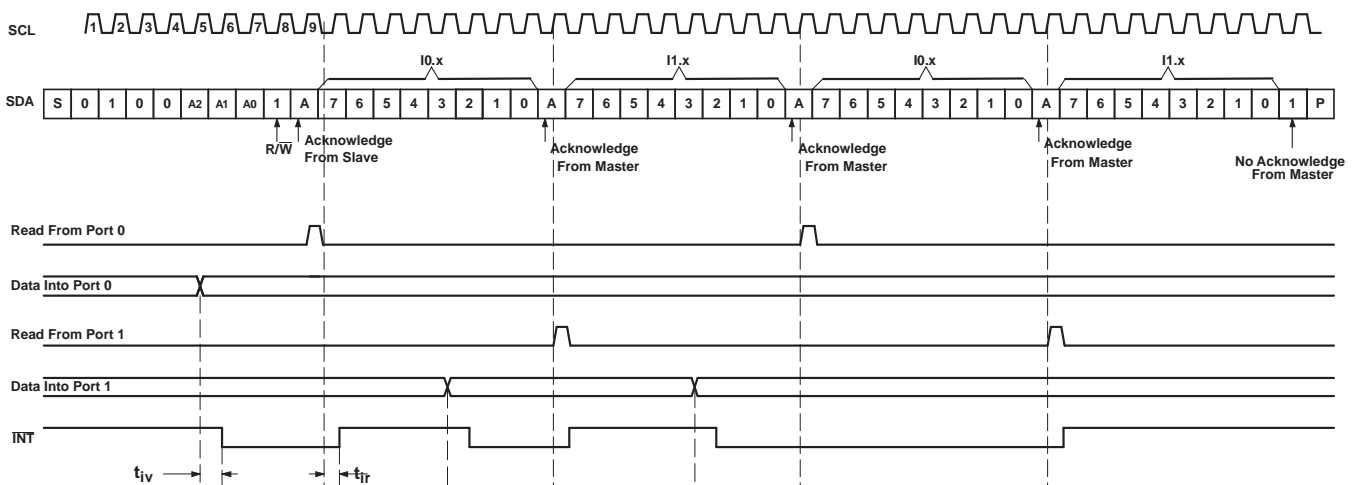
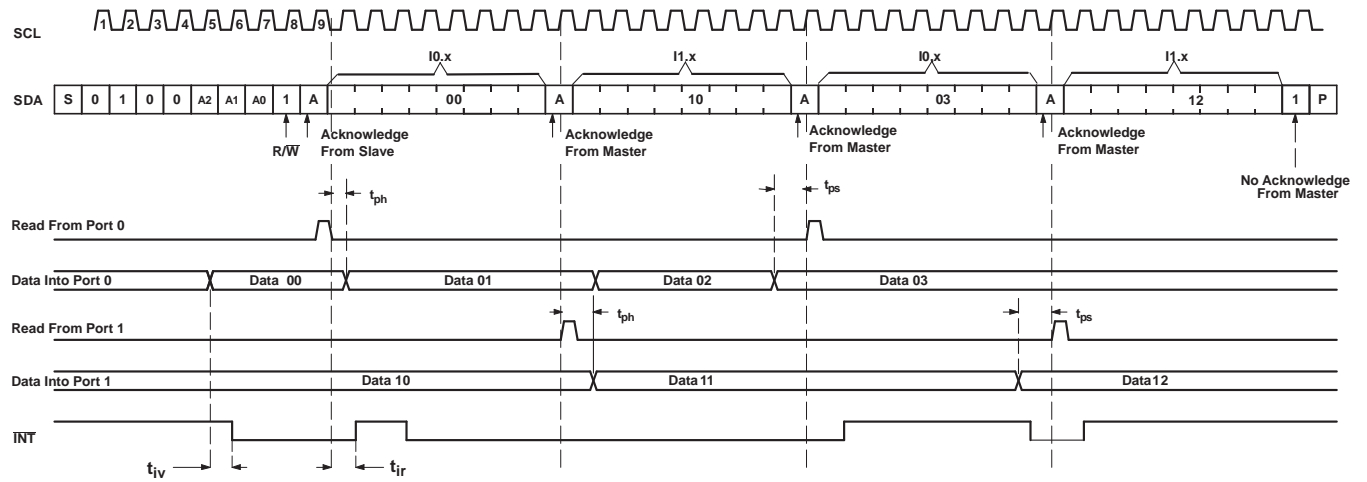


Figure 8. Read From Register



- A. Transfer of data can be stopped at any time by a Stop condition. When this occurs, data present at the latest acknowledge phase is valid (output mode). It is assumed that the command byte previously has been set to 00 (read Input Port register).
- B. This figure eliminates the command byte transfer, a restart, and slave address call between the initial slave address call and actual data transfer from the P port (see Figure 8 for these details).

Figure 9. Read Input Port Register, Scenario 1



- A. Transfer of data can be stopped at any time by a Stop condition. When this occurs, data present at the latest acknowledge phase is valid (output mode). It is assumed that the command byte previously has been set to 00 (read Input Port register).
- B. This figure eliminates the command byte transfer, a restart, and slave address call between the initial slave address call and actual data transfer from the P port (see [Figure 8](#) for these details).

Figure 10. Read Input Port Register, Scenario 2

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

| | | MIN | MAX | UNIT |
|---------------|--|-----------------------------|------|------|
| V_{CC} | Supply voltage range | –0.5 | 6 | V |
| V_I | Input voltage range ⁽²⁾ | –0.5 | 6 | V |
| V_O | Output voltage range ⁽²⁾ | –0.5 | 6 | V |
| I_{IK} | Input clamp current | $V_I < 0$ | –20 | mA |
| I_{OK} | Output clamp current | $V_O < 0$ | –20 | mA |
| I_{IOK} | Input/output clamp current | $V_O < 0$ or $V_O > V_{CC}$ | ±20 | mA |
| I_{OL} | Continuous output low current | $V_O = 0$ to V_{CC} | 50 | mA |
| I_{OH} | Continuous output high current | $V_O = 0$ to V_{CC} | –50 | mA |
| I_{CC} | Continuous current through GND | | –250 | mA |
| | Continuous current through V_{CC} | | 160 | |
| θ_{JA} | Package thermal impedance, junction to free air ⁽³⁾ | PW package | 88 | °C/W |
| | | RTW package | 66 | |
| T_{stg} | Storage temperature range | –65 | 150 | °C |

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) The package thermal impedance is calculated in accordance with JESD 51-7.

RECOMMENDED OPERATING CONDITIONS

| | | MIN | MAX | UNIT |
|----------|--------------------------------|-------------------------|---------------------|---------------------|
| V_{CC} | Supply voltage | 1.65 | 5.5 | V |
| V_{IH} | High-level input voltage | SCL, SDA | $0.7 \times V_{CC}$ | 5.5 |
| | | A2–A0, P07–P00, P17–P10 | $0.7 \times V_{CC}$ | 5.5 |
| V_{IL} | Low-level input voltage | SCL, SDA | –0.5 | $0.3 \times V_{CC}$ |
| | | A2–A0, P07–P00, P17–P10 | –0.5 | $0.3 \times V_{CC}$ |
| I_{OH} | High-level output current | P07–P00, P17–P10 | –10 | mA |
| I_{OL} | Low-level output current | P07–P00, P17–P10 | 25 | mA |
| T_A | Operating free-air temperature | –40 | 85 | °C |

ELECTRICAL CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | | TEST CONDITIONS | V _{CC} | MIN | TYP ⁽¹⁾ | MAX | UNIT | |
|------------------|---|---|---|--------|--------------------|------|------|----|
| V _{IK} | Input diode clamp voltage | I _I = -18 mA | 1.65 V to 5.5 V | -1.2 | | | V | |
| V _{POR} | Power-on reset voltage | V _I = V _{CC} or GND, I _O = 0 | 1.65 V to 5.5 V | | 1.5 | 1.65 | V | |
| V _{OH} | P-port high-level output voltage ⁽²⁾ | I _{OH} = -8 mA | 1.65 V | 1.2 | | | V | |
| | | | 2.3 V | 1.8 | | | | |
| | | | 3 V | 2.6 | | | | |
| | | | 4.75 V | 4.1 | | | | |
| | | I _{OH} = -10 mA | 1.65 V | 1.8 | | | | |
| | | | 2.3 V | 1.7 | | | | |
| | | | 3 V | 2.5 | | | | |
| | | | 4.75 V | 4 | | | | |
| I _{OL} | SDA | V _{OL} = 0.4 V | 1.65 V to 5.5 V | | 3 | | mA | |
| | P port ⁽³⁾ | V _{OL} = 0.5 V | | 8 | 20 | | | |
| | | V _{OL} = 0.7 V | | 10 | 24 | | | |
| | $\overline{\text{INT}}$ | V _{OL} = 0.4 V | | | 3 | | | |
| I _I | SCL, SDA | V _I = V _{CC} or GND | 1.65 V to 5.5 V | | | ±1 | μA | |
| | A2–A0 | | | | | ±1 | | |
| I _{IH} | P port | V _I = V _{CC} | 1.65 V to 5.5 V | | | 1 | μA | |
| I _{IL} | P port | V _I = GND | 1.65 V to 5.5 V | | | -100 | μA | |
| I _{CC} | Operating mode | | V _I = V _{CC} or GND, I _O = 0, I/O = inputs, f _{SCL} = 400 kHz, No load | 5.5 V | | 100 | 200 | μA |
| | | | | 3.6 V | | 30 | 75 | |
| | | | | 2.7 V | | 20 | 50 | |
| | | | | 1.95 V | | 10 | 45 | |
| | Standby mode | Low inputs | V _I = GND, I _O = 0, I/O = inputs, f _{SCL} = 0 kHz, No load | 5.5 V | | 1.1 | 1.5 | mA |
| | | | | 3.6 V | | 0.7 | 1.3 | |
| | | | | 2.7 V | | 0.5 | 1 | |
| | | | | 1.95 V | | 0.3 | 0.9 | |
| | | High inputs | V _I = V _{CC} , I _O = 0, I/O = inputs, f _{SCL} = 0 kHz, No load | 5.5 V | | 2.5 | 3 | μA |
| | | | | 3.6 V | | 2 | 2.6 | |
| | | | | 2.7 V | | 1.5 | 2.5 | |
| | | | | 1.95 V | | 1.2 | 2.3 | |
| ΔI _{CC} | Additional current in standby mode | One input at V _{CC} - 0.6 V, Other inputs at V _{CC} or GND | 1.65 V to 5.5 V | | | 1.5 | mA | |
| C _I | SCL | V _I = V _{CC} or GND | 1.65 V to 5.5 V | | 3 | 7 | pF | |
| C _{io} | SDA | V _{IO} = V _{CC} or GND | 1.65 V to 5.5 V | | 3 | 7 | pF | |
| | P port | | | | 3.7 | 9.5 | | |

(1) All typical values are at nominal supply voltage (1.8-V, 2.5-V, 3.3-V, or 5-V V_{CC}) and T_A = 25°C.

(2) Each I/O must be externally limited to a maximum of 25 mA, and each octal (P07–P00 and P17–P10) must be limited to a maximum current of 100 mA, for a device total of 200 mA.

(3) The total current sourced by all I/Os must be limited to 160 mA (80 mA for P07–P00 and 80 mA for P17–P10).

I²C INTERFACE TIMING REQUIREMENTS

over recommended operating free-air temperature range (unless otherwise noted) (see [Figure 11](#))

| | | MIN | MAX | UNIT | |
|----------------|--|--|---------------|------|----|
| f_{scl} | I ² C clock frequency | 0 | 400 | kHz | |
| t_{sch} | I ² C clock high time | 0.6 | | μs | |
| t_{scl} | I ² C clock low time | 1.3 | | μs | |
| t_{sp} | I ² C spike time | | 50 | ns | |
| t_{sds} | I ² C serial-data setup time | 100 | | ns | |
| t_{sdh} | I ² C serial-data hold time | 0 | | ns | |
| t_{icr} | I ² C input rise time | $20 + 0.1C_b$ | 300 | ns | |
| t_{icf} | I ² C input fall time | $20 + 0.1C_b$ | 300 | ns | |
| t_{ocf} | I ² C output fall time | 10-pF to 400-pF bus | $20 + 0.1C_b$ | 300 | ns |
| t_{buf} | I ² C bus free time between Stop and Start | 1.3 | | μs | |
| t_{sts} | I ² C Start or repeated Start condition setup | 0.6 | | μs | |
| t_{sth} | I ² C Start or repeated Start condition hold | 0.6 | | μs | |
| t_{sps} | I ² C Stop condition setup | 0.6 | | μs | |
| $t_{vd(Data)}$ | Valid-data time | SCL low to SDA output valid | 50 | ns | |
| $t_{vd(ack)}$ | Valid-data time of ACK condition | ACK signal from SCL low to SDA (out) low | 0.1 | 0.9 | μs |
| C_b | I ² C bus capacitive load | | 400 | pF | |

SWITCHING CHARACTERISTICS

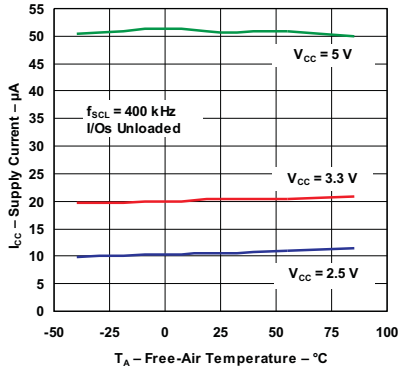
over recommended operating free-air temperature range, $C_L \leq 100$ pF (unless otherwise noted) (see [Figure 12](#) and [Figure 13](#))

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | MIN | MAX | UNIT |
|-----------|----------------------------|-------------|-----|-----|------|
| t_{iv} | Interrupt valid time | P port | | 4 | μs |
| t_{ir} | Interrupt reset delay time | SCL | | 4 | μs |
| t_{pv} | Output data valid | SCL | | 200 | ns |
| t_{ps} | Input data setup time | P port | 150 | | ns |
| t_{ph} | Input data hold time | P port | 1 | | μs |

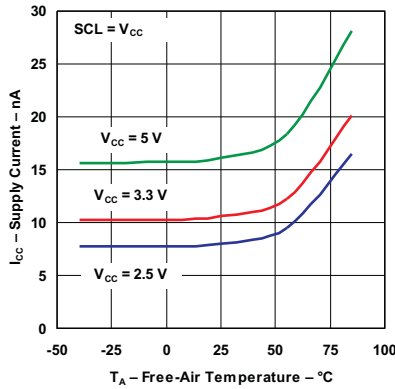
TYPICAL CHARACTERISTICS

$T_A = 25^\circ\text{C}$ (unless otherwise noted)

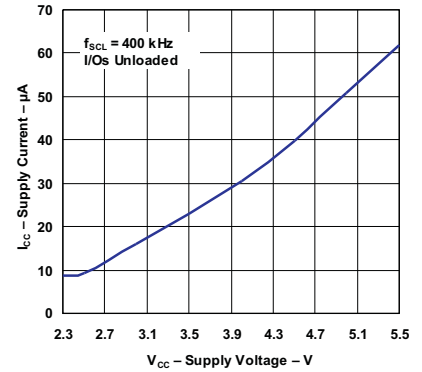
**SUPPLY CURRENT
VS
TEMPERATURE**



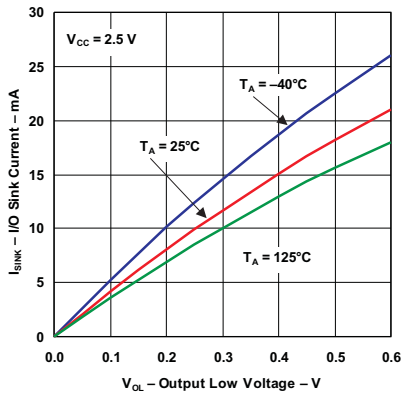
**STANDBY SUPPLY CURRENT
VS
TEMPERATURE**



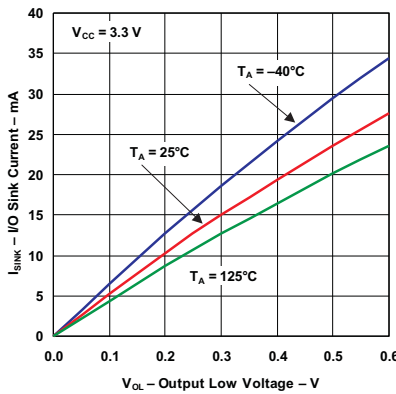
**SUPPLY CURRENT
VS
SUPPLY VOLTAGE**



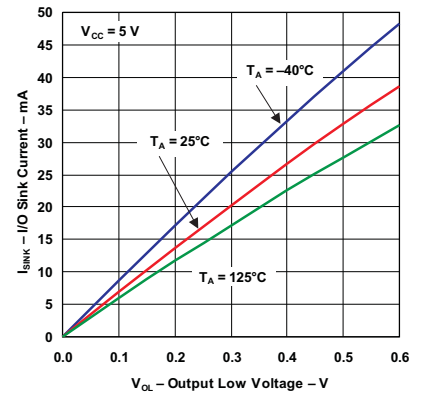
**I/O SINK CURRENT
VS
OUTPUT LOW VOLTAGE**



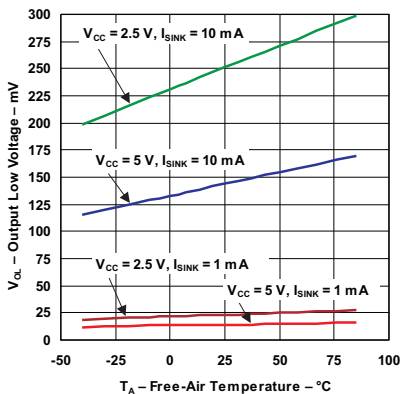
**I/O SINK CURRENT
VS
OUTPUT LOW VOLTAGE**



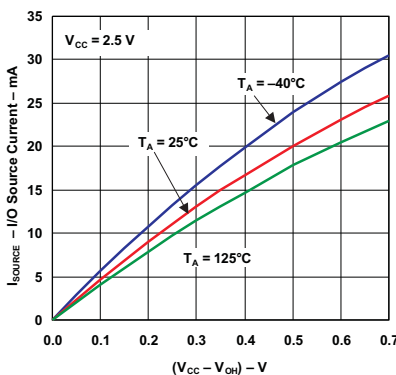
**I/O SINK CURRENT
VS
OUTPUT LOW VOLTAGE**



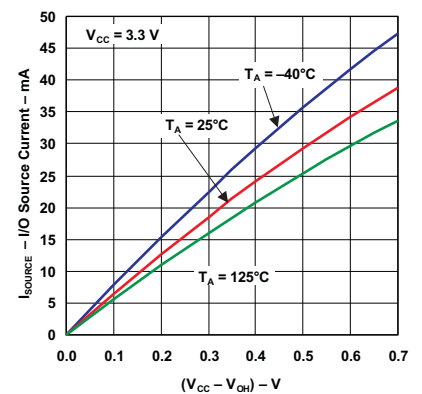
**I/O OUTPUT LOW VOLTAGE
VS
TEMPERATURE**



**I/O SOURCE CURRENT
VS
OUTPUT HIGH VOLTAGE**



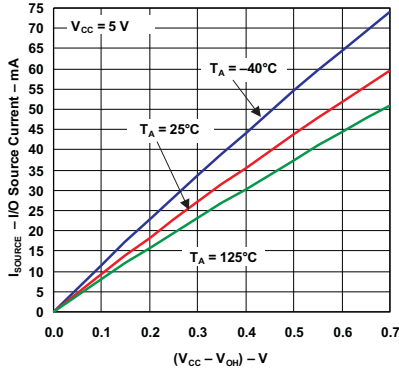
**I/O SOURCE CURRENT
VS
OUTPUT HIGH VOLTAGE**



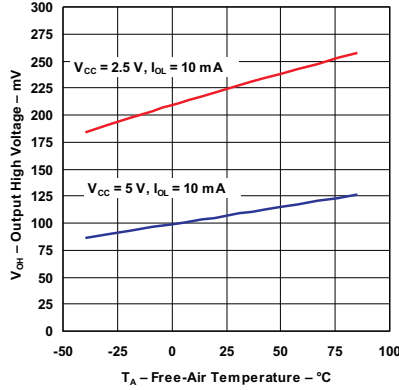
TYPICAL CHARACTERISTICS (continued)

$T_A = 25^\circ\text{C}$ (unless otherwise noted)

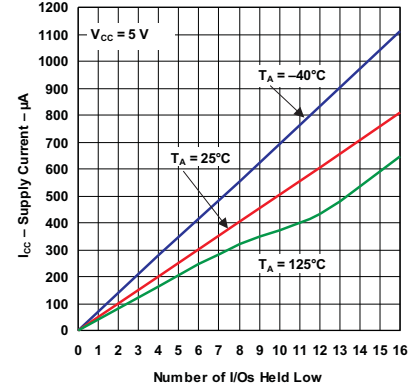
**I/O SOURCE CURRENT
VS
OUTPUT HIGH VOLTAGE**



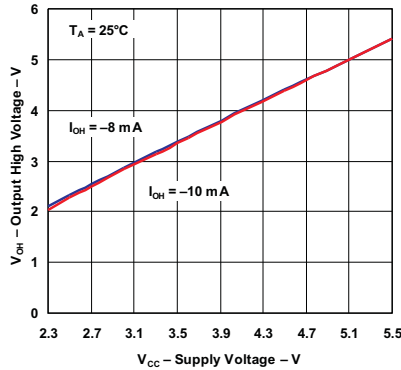
**I/O HIGH VOLTAGE
VS
TEMPERATURE**



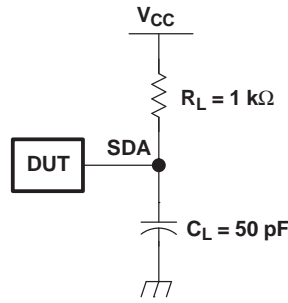
**SUPPLY CURRENT
VS
NUMBER OF I/Os HELD LOW**



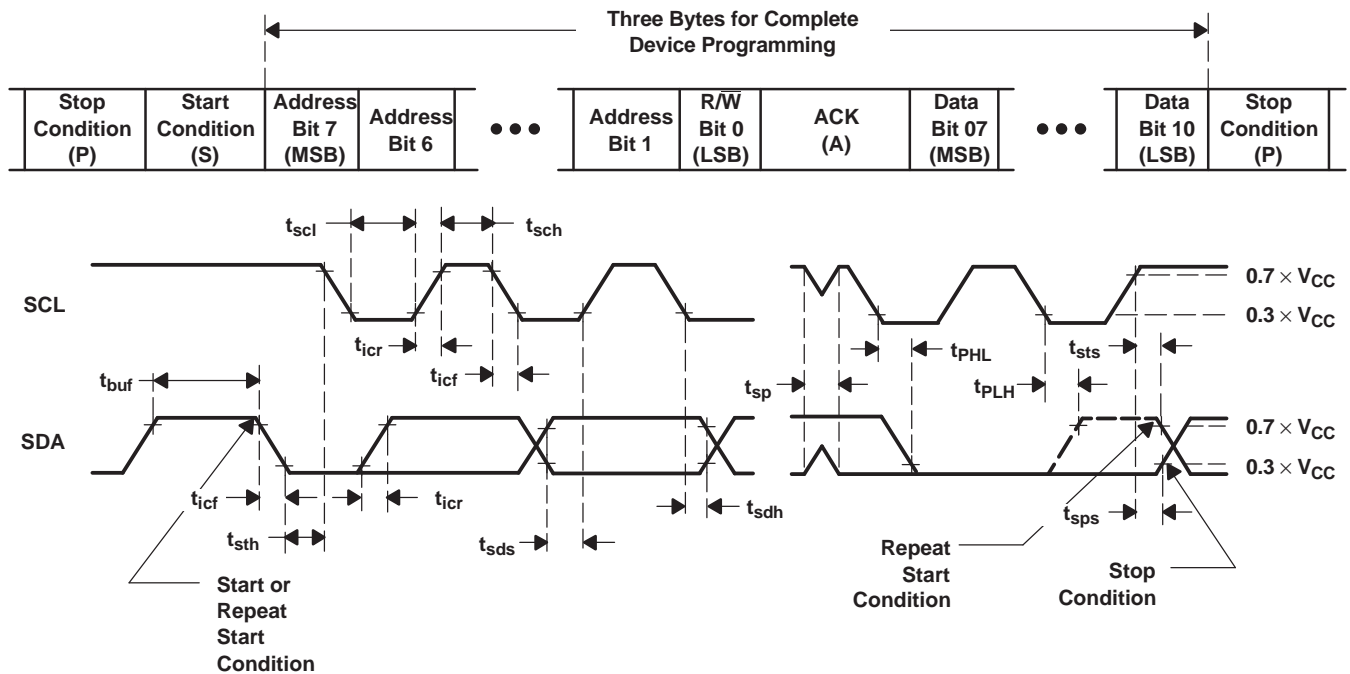
**OUTPUT HIGH VOLTAGE
VS
SUPPLY VOLTAGE**



PARAMETER MEASUREMENT INFORMATION



SDA LOAD CONFIGURATION



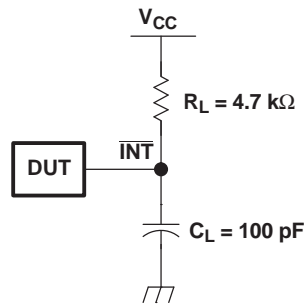
VOLTAGE WAVEFORMS

| BYTE | DESCRIPTION |
|------|--------------------------|
| 1 | I ² C address |
| 2, 3 | P-port data |

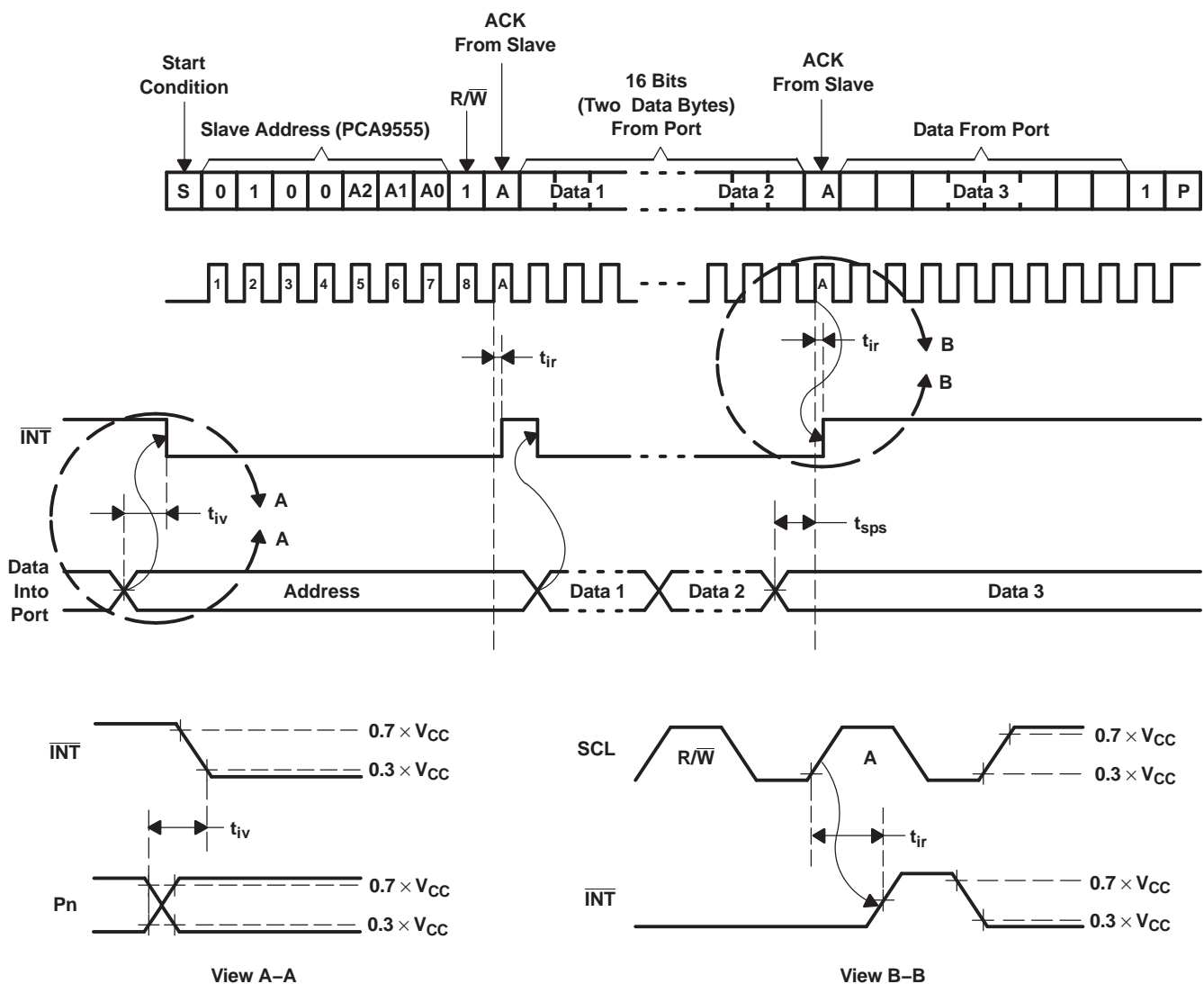
- A. C_L includes probe and jig capacitance.
- B. All inputs are supplied by generators having the following characteristics: $PRR \leq 10$ MHz, $Z_O = 50 \Omega$, $t_r/t_f \leq 30$ ns.
- C. All parameters and waveforms are not applicable to all devices.

Figure 11. I²C Interface Load Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION (continued)



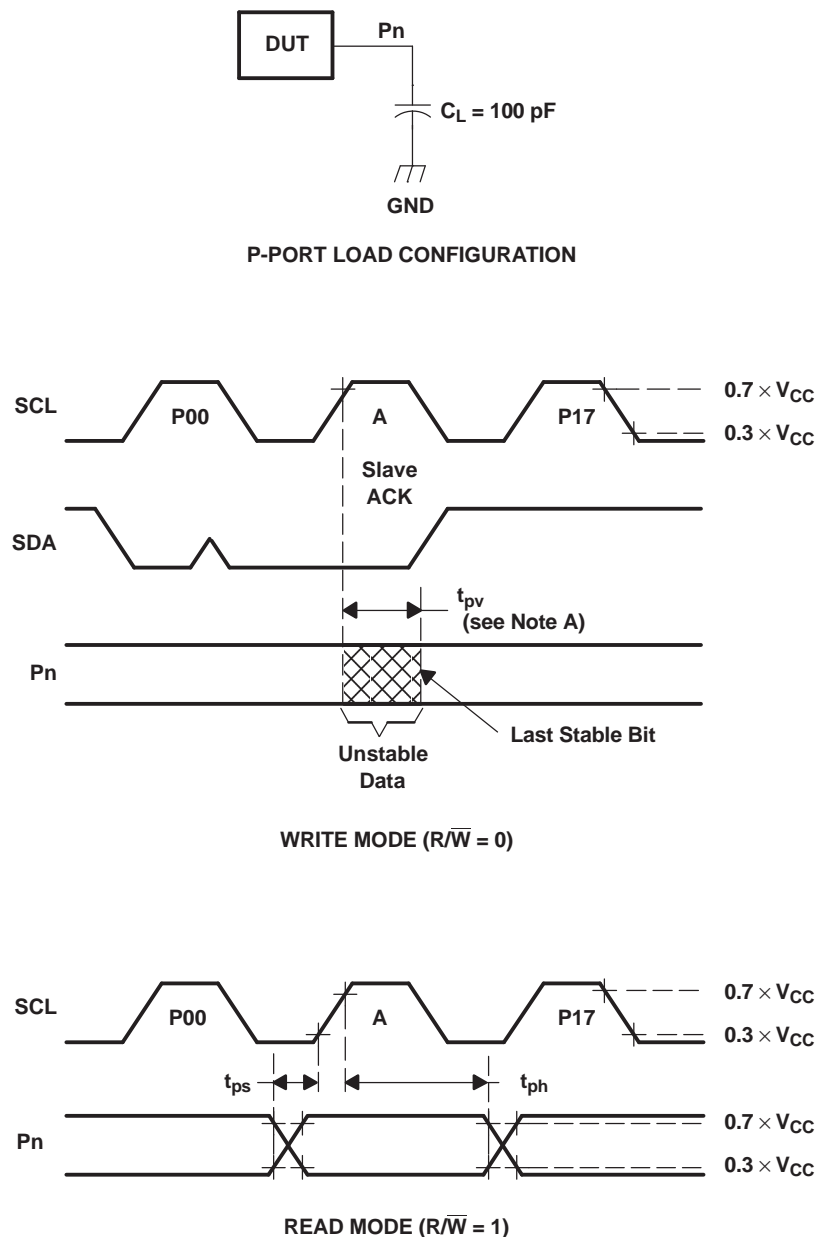
INTERRUPT LOAD CONFIGURATION



- A. C_L includes probe and jig capacitance.
- B. All inputs are supplied by generators having the following characteristics: $PRR \leq 10$ MHz, $Z_O = 50 \Omega$, $t_r/t_f \leq 30$ ns.
- C. All parameters and waveforms are not applicable to all devices.

Figure 12. Interrupt Load Circuit and Voltage Waveforms

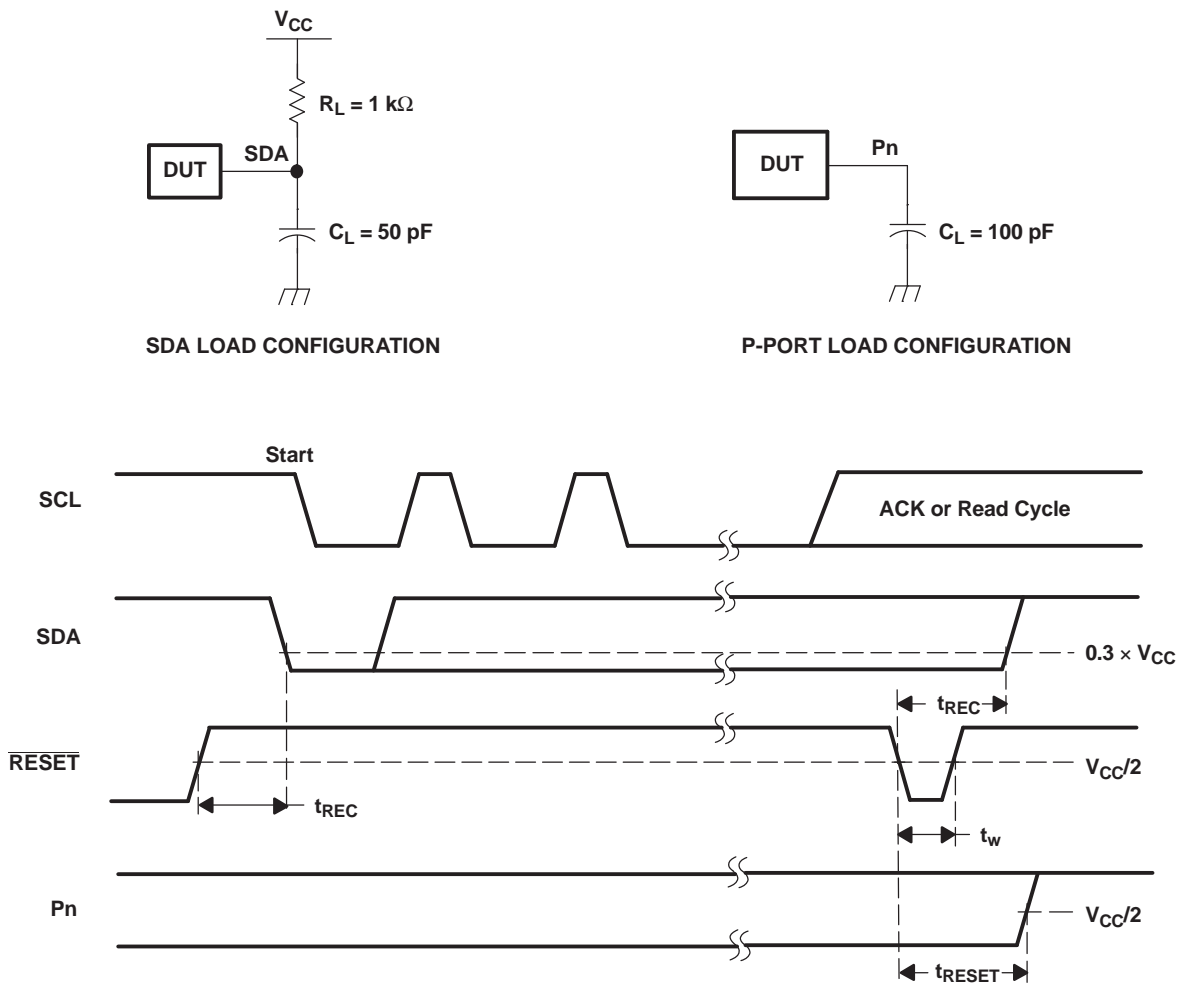
PARAMETER MEASUREMENT INFORMATION (continued)



- A. C_L includes probe and jig capacitance.
- B. t_{pv} is measured from $0.7 \times V_{CC}$ on SCL to 50% I/O (Pn) output.
- C. All inputs are supplied by generators having the following characteristics: $PRR \leq 10$ MHz, $Z_O = 50 \Omega$, $t_r/t_f \leq 30$ ns.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. All parameters and waveforms are not applicable to all devices.

Figure 13. P-Port Load Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION (continued)

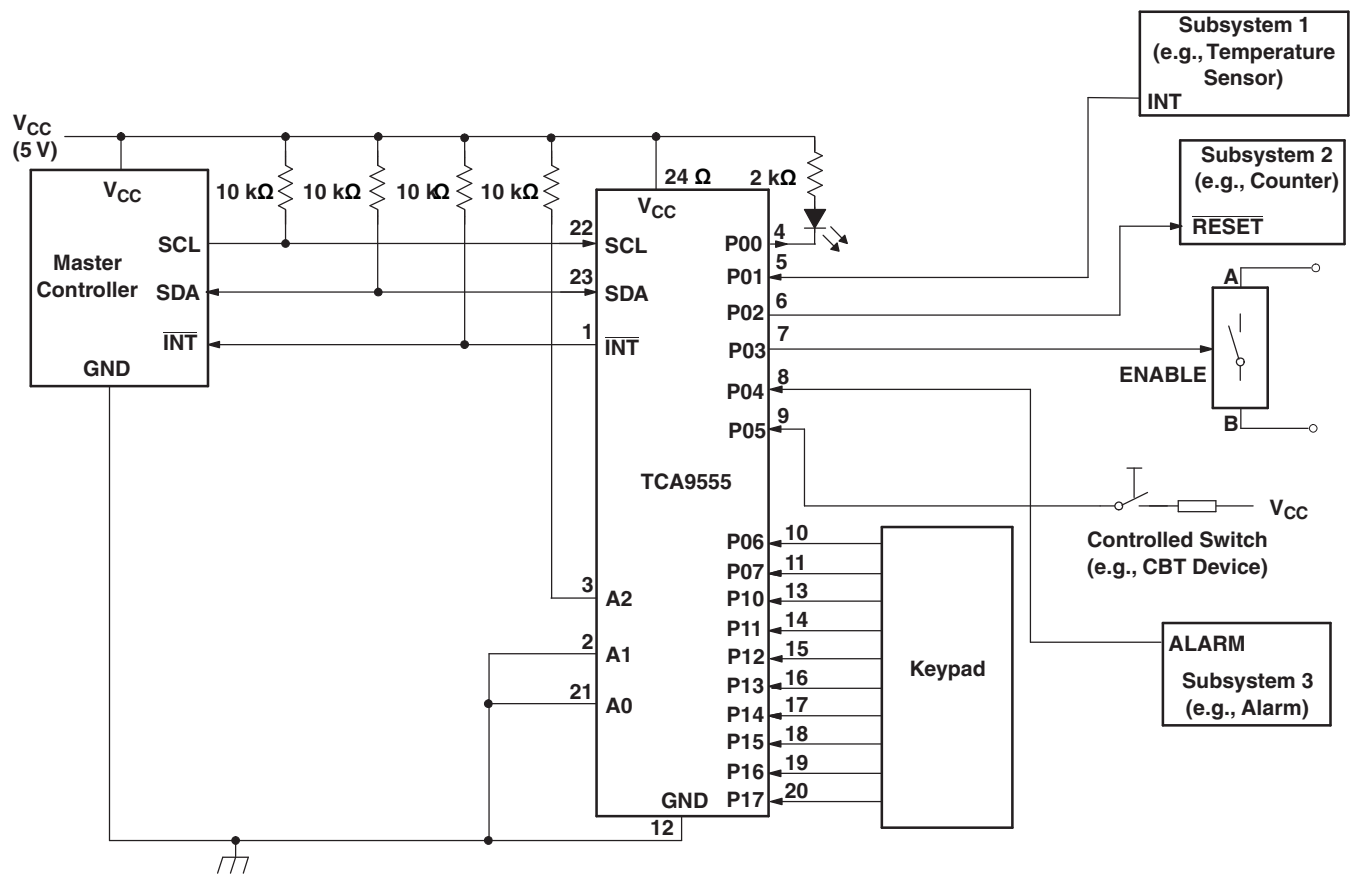


- A. C_L includes probe and jig capacitance.
- B. All inputs are supplied by generators having the following characteristics: $PRR \leq 10$ MHz, $Z_O = 50 \Omega$, $t_r/t_f \leq 30$ ns.
- C. The outputs are measured one at a time, with one transition per measurement.
- D. I/Os are configured as inputs.
- E. All parameters and waveforms are not applicable to all devices.

Figure 14. Reset Load Circuits and Voltage Waveforms

APPLICATION INFORMATION

Figure 15 shows an application in which the TCA9555 can be used.



- Device address is configured as 0100100 for this example.
- P00, P02, and P03 are configured as outputs.
- P01, P04–P07, and P10–P17 are configured as inputs.
- Pin numbers shown are for the PW package.

Figure 15. Typical Application

Minimizing I_{CC} When I/O Is Used to Control LED

When an I/O is used to control an LED, normally it is connected to V_{CC} through a resistor as shown in Figure 15. Because the LED acts as a diode, when the LED is off, the I/O V_{IN} is about 1.2 V less than V_{CC} . The ΔI_{CC} parameter in Electrical Characteristics shows how I_{CC} increases as V_{IN} becomes lower than V_{CC} . For battery-powered applications, it is essential that the voltage of I/O pins is greater than or equal to V_{CC} when the LED is off to minimize current consumption.

Figure 16 shows a high-value resistor in parallel with the LED. Figure 17 shows V_{CC} less than the LED supply voltage by at least 1.2 V. Both of these methods maintain the I/O V_{IN} at or above V_{CC} and prevent additional supply current consumption when the LED is off.

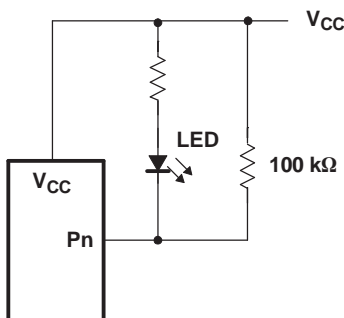


Figure 16. High-Value Resistor in Parallel With LED

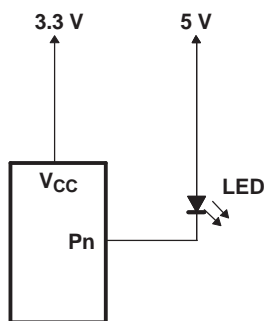


Figure 17. Device Supplied by Lower Voltage

Power-On Reset Requirements

In the event of a glitch or data corruption, TCA9555 can be reset to its default conditions by using the power-on reset feature. Power-on reset requires that the device go through a power cycle to be completely reset. This reset also happens when the device is powered on for the first time in an application.

The two types of power-on reset are shown in Figure 18 and Figure 19.

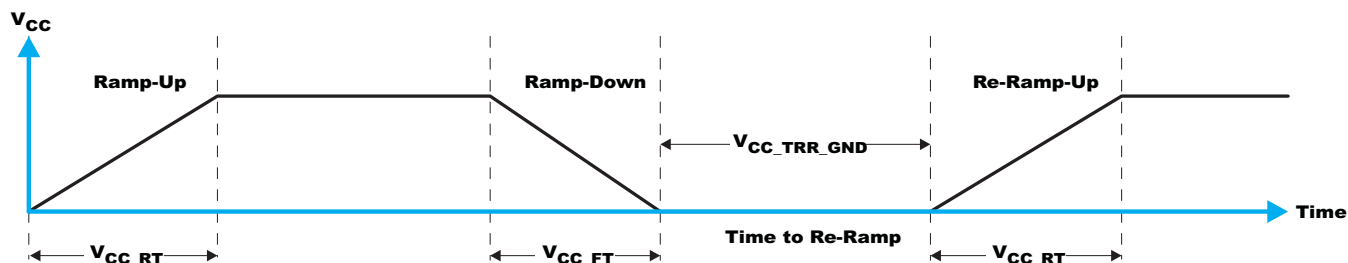


Figure 18. V_{CC} is Lowered Below 0.2 V or 0 V and Then Ramped Up to V_{CC}

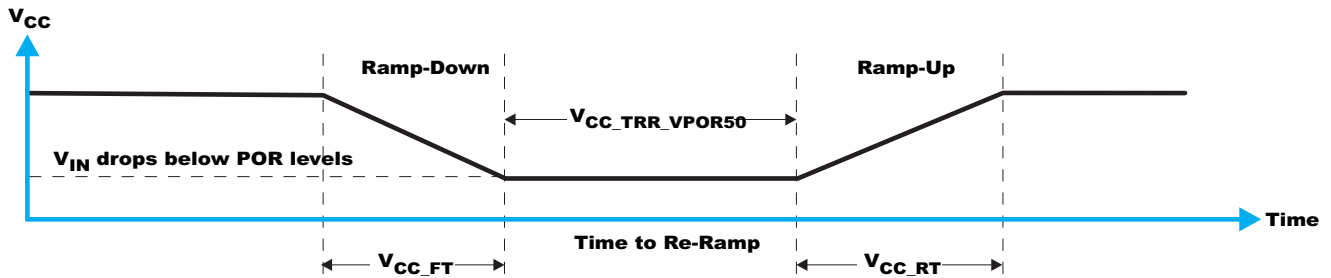


Figure 19. V_{CC} is Lowered Below the POR Threshold, Then Ramped Back Up to V_{CC}

Table 1 specifies the performance of the power-on reset feature for TCA9555 for both types of power-on reset.

Table 1. RECOMMENDED SUPPLY SEQUENCING AND RAMP RATES⁽¹⁾

| PARAMETER | | | MIN | TYP | MAX | UNIT |
|----------------------|---|---------------|-----|------|-----|---------|
| V_{CC_FT} | Fall rate | See Figure 18 | 0.1 | 2000 | | ms |
| V_{CC_RT} | Rise rate | See Figure 18 | 0.1 | 2000 | | ms |
| $V_{CC_TRR_GND}$ | Time to re-ramp (when V_{CC} drops to GND) | See Figure 18 | 1 | | | μ s |
| $V_{CC_TRR_POR50}$ | Time to re-ramp (when V_{CC} drops to $V_{POR_MIN} - 50$ mV) | See Figure 19 | 1 | | | μ s |
| V_{CC_GH} | Level that V_{CCP} can glitch down to, but not cause a functional disruption when $V_{CCX_GW} = 1$ μ s | See Figure 20 | | | 1.2 | V |
| V_{CC_GW} | Glitch width that will not cause a functional disruption when $V_{CCX_GH} = 0.5 \times V_{CCx}$ | See Figure 20 | | | 10 | μ s |
| V_{PORF} | Voltage trip point of POR on falling V_{CC} | | 0.7 | | | V |
| V_{PORR} | Voltage trip point of POR on rising V_{CC} | | | | 1.4 | V |

(1) $T_A = -40^\circ\text{C}$ to 85°C (unless otherwise noted)

Glitches in the power supply can also affect the power-on reset performance of this device. The glitch width (V_{CC_GW}) and height (V_{CC_GH}) are dependent on each other. The bypass capacitance, source impedance, and device impedance are factors that affect power-on reset performance. Figure 20 and Table 1 provide more information on how to measure these specifications.

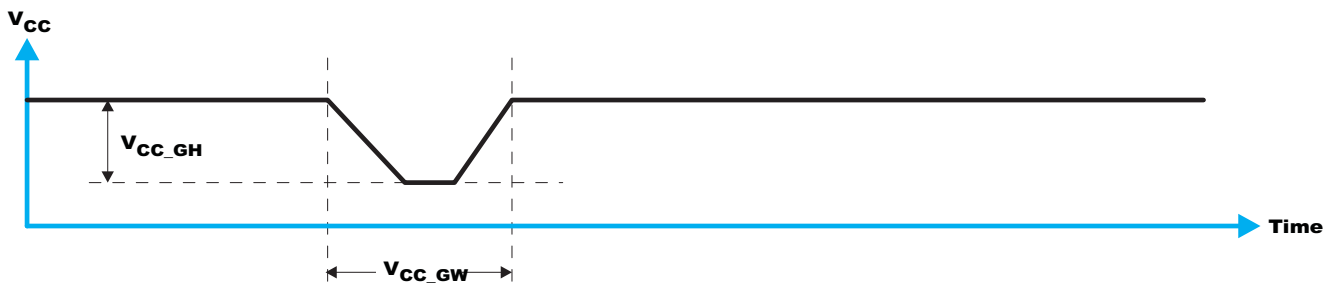


Figure 20. Glitch Width and Glitch Height

V_{POR} is critical to the power-on reset. V_{POR} is the voltage level at which the reset condition is released and all the registers and the I²C/SMBus state machine are initialized to their default states. The value of V_{POR} differs based on the V_{CC} being lowered to or from 0. Figure 21 and Table 1 provide more details on this specification.

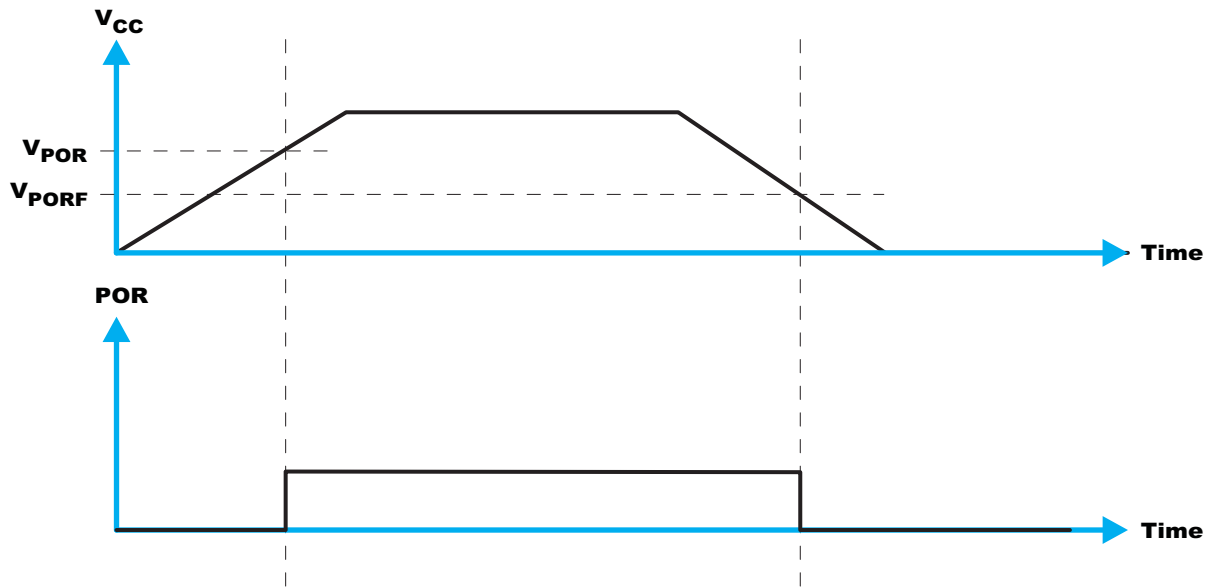


Figure 21. V_{POR}

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish | MSL Peak Temp (3) | Op Temp (°C) | Top-Side Markings (4) | Samples |
|------------------|---------------|--------------|--------------------|------|-------------|----------------------------|------------------|----------------------|--------------|--------------------------|-------------------------|
| TCA9555PWR | ACTIVE | TSSOP | PW | 24 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | PW555 | Samples |
| TCA9555RTWR | ACTIVE | WQFN | RTW | 24 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | -40 to 85 | PW555 | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Only one of markings shown within the brackets will appear on the physical device.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION



QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|-------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| TCA9555RTWR | WQFN | RTW | 24 | 3000 | 330.0 | 12.4 | 4.25 | 4.25 | 1.15 | 8.0 | 12.0 | Q2 |

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|-------------|--------------|-----------------|------|------|-------------|------------|-------------|
| TCA9555RTWR | WQFN | RTW | 24 | 3000 | 367.0 | 367.0 | 35.0 |

MECHANICAL DATA

PW (R-PDSO-G24)

PLASTIC SMALL OUTLINE

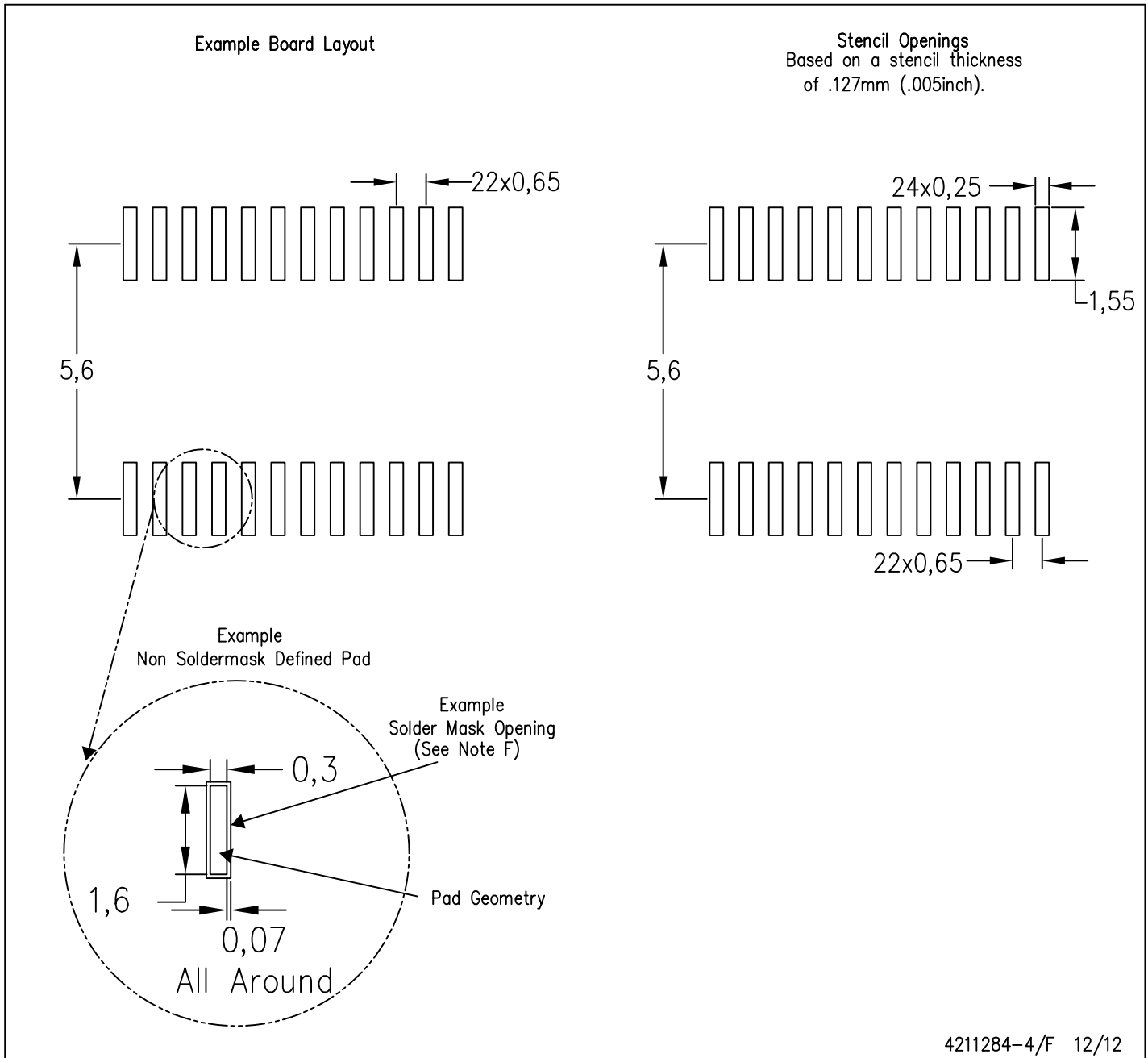


4040064-6/G 02/11

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
 - Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
 - E. Falls within JEDEC MO-153

PW (R-PDSO-G24)

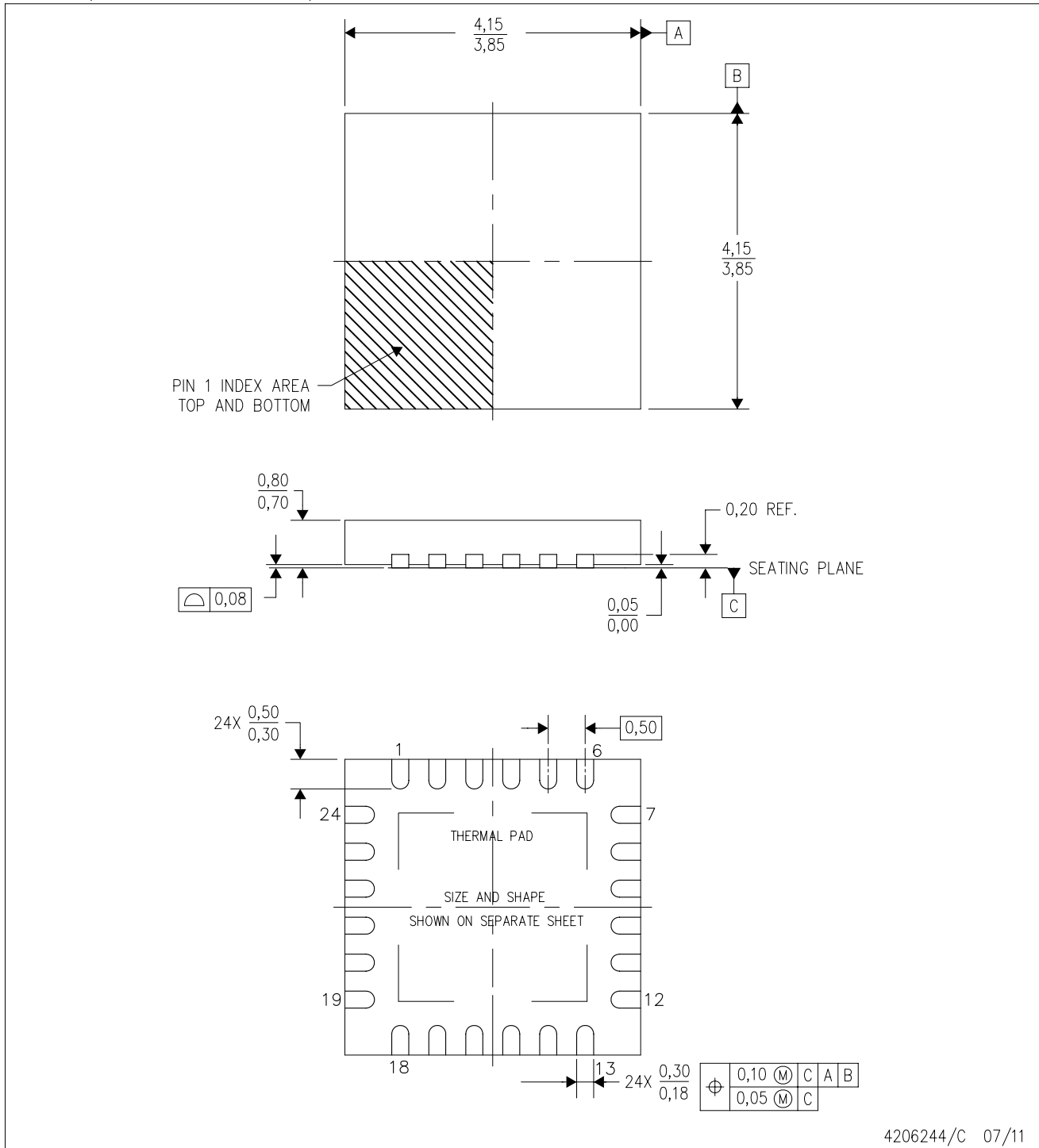
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate design.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

RTW (S-PWQFN-N24)

PLASTIC QUAD FLATPACK NO-LEAD



4206244/C 07/11

- NOTES:
- All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - This drawing is subject to change without notice.
 - Quad Flatpack, No-Leads (QFN) package configuration.
 - The package thermal pad must be soldered to the board for thermal and mechanical performance.
 - See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
 - Falls within JEDEC MO-220.

THERMAL PAD MECHANICAL DATA

RTW (S-PWQFN-N24)

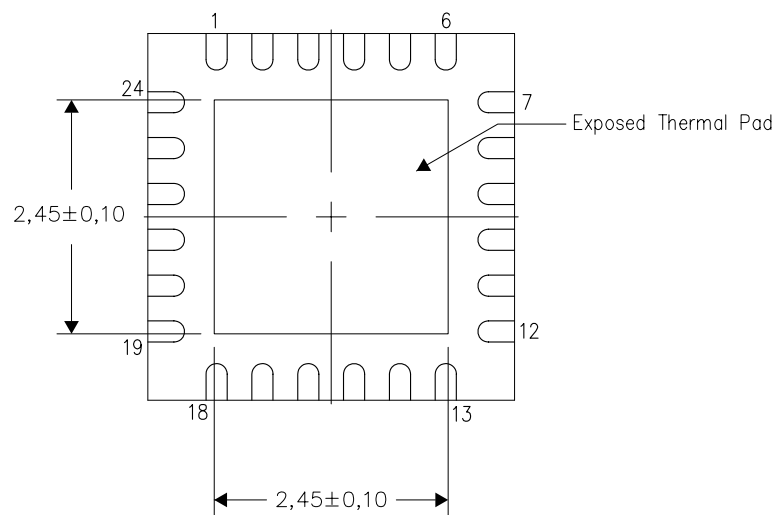
PLASTIC QUAD FLATPACK NO-LEAD

THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No-Lead (QFN) package and its advantages, refer to Application Report, QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271. This document is available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.

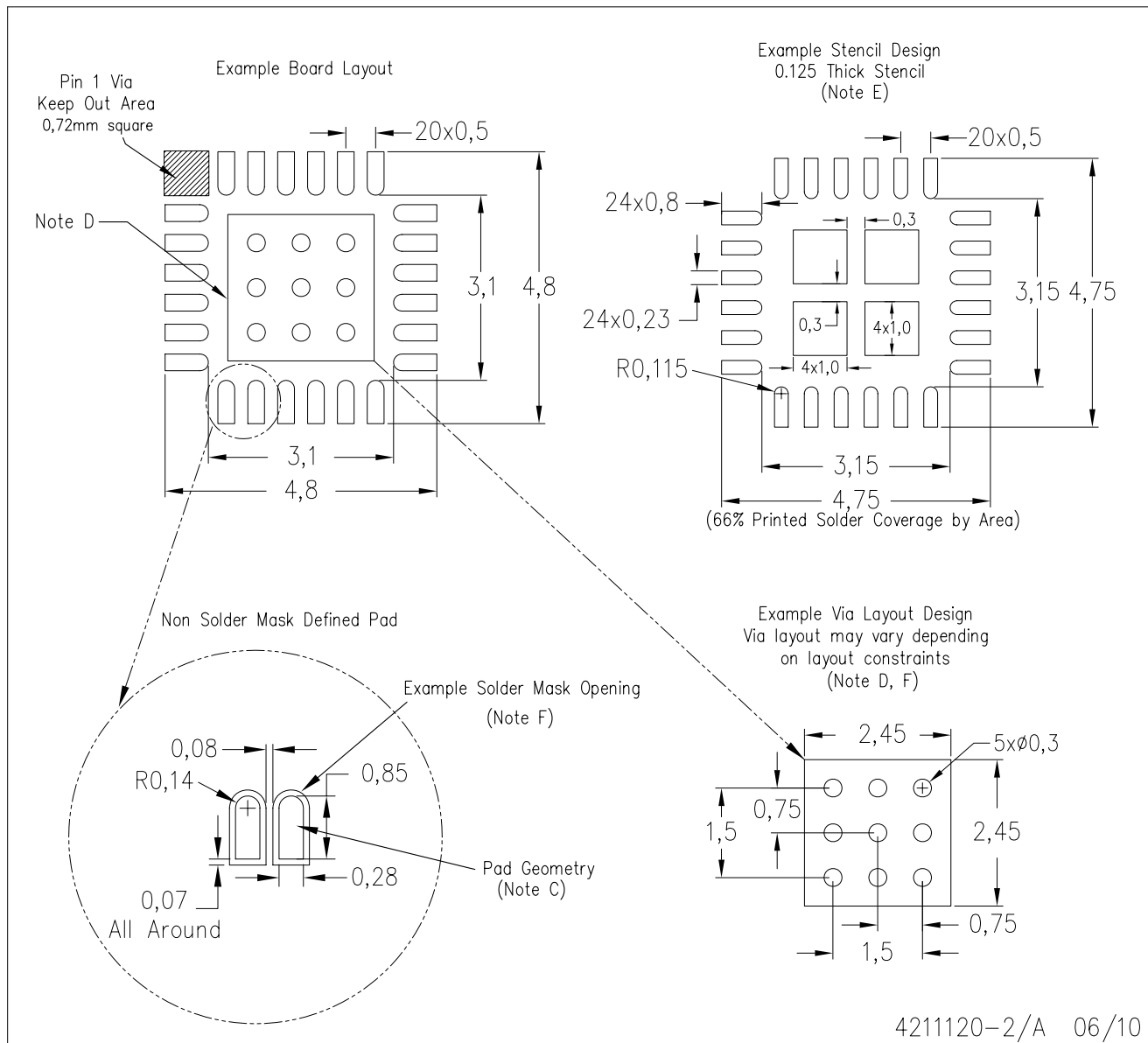


4206249-3/L 07/11

NOTES: A. All linear dimensions are in millimeters

RTW (S-PWQFN-N24)

PLASTIC QUAD FLATPACK NO-LEAD



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, Quad Flat-Pack Packages, Texas Instruments Literature No. SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com <<http://www.ti.com>>.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
 - Customers should contact their board fabrication site for recommended solder mask tolerances and via tenting recommendations for vias placed in the thermal pad.

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